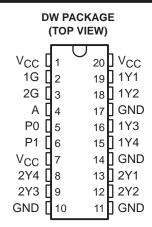
- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Eight Outputs
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I<sub>OH</sub>, 48-mA I<sub>OI</sub> )
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Packaging Options Include Plastic Small-Outline (DW) Packages



### description

The CDC341 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a low state regardless of the A input.

The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The CDC341 is characterized for operation from 0°C to 70°C.

**FUNCTION TABLE** 

	INPUTS		OUTPUTS				
1G	2G	Α	1Y1-1Y4	2Y1-2Y4			
Х	Х	L	L	L			
L	L	Н	L	L			
L	Н	Н	L	Н			
Н	L	Н	Н	L			
Н	Н	Н	Н	Н			

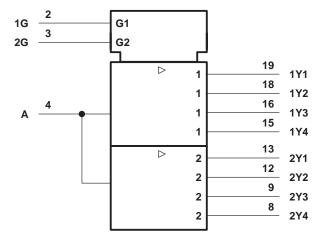


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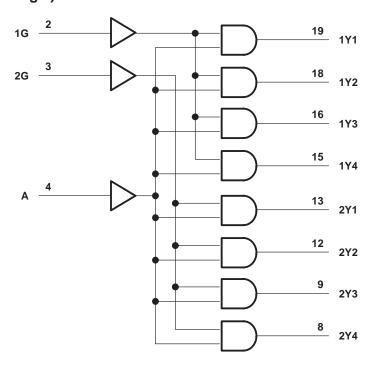


## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Sı	upply voltage range, V <sub>CC</sub>	0.5 V to 7 V
In	put voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Vo	oltage range applied to any output in the high state or power-off state,	
\	V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
C	urrent into any output in the low state, IO	96 mA
In	put clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
M	aximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2)	1.6 W
St	orage temperature range, T <sub>stq</sub>	$\dots$ -65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		4.75	5.25	V
VIH	High-level input voltage	2		V	
V <sub>IL</sub>	Low-level input voltage		0.8	V	
VI	Input voltage	0	VCC	V	
IOH	High-level output current		-48	mA	
loL	Low-level output current			48	mA
f	Input clock frequency	One output bank loaded		80	MHz
fclock	input clock frequency	Both output banks loaded		40	IVII 1Z
TA	Operating free-air temperature	0	70	°C	

NOTE 3: Unused pins (input or I/O) must be held high or low.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	_	EST CONDITIONS		Т	A = 25°C	;	MIN	MAX	UNIT
PARAWETER	"	MIN	TYP <sup>†</sup>	MAX	IVIIIV	IVIAA	UNIT		
VIK	$V_{CC} = 4.75 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2		-1.2	V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		
Voн	$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$		3			3		V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -48 \text{ mA}$		2			2		
V <sub>OL</sub>	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 48 \text{ mA}$						0.5	V
lį	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1	μΑ
lo <sup>‡</sup>	$V_{CC} = 5.25 \text{ V},$	V <sub>O</sub> = 2.5 V		-50	-100	-200	-50	-200	mA
laa	V <sub>CC</sub> = 5.25 V,	I <sub>O</sub> = 0,	Outputs high		2			3.5	mA
lcc	$V_I = V_{CC}$ or GND		Outputs low		24			33	IIIA
Ci	$V_{ } = 2.5 \text{ V or } 0.5 \text{ V}$	·			3				pF

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

# switching characteristics, $C_L$ = 50 pF (see Figures 1 and 2)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.75 T <sub>A</sub> = 0°	UNIT	
	(INPUT)	(001701)	MIN	TYP	MAX	MIN	MAX	
<sup>t</sup> PLH	А	V	3.5		4.5	3.1	4.9	ns
t <sub>PHL</sub>	Α	'	3.5		4.3	3.1	4.9	115
<sup>t</sup> PLH	G	V	2		3.8	2	4	ns
<sup>t</sup> PHL		ı	2		3.8	2	4	115
tsk(o)				0.3	0.5		0.6	
<sup>t</sup> sk(p)	Α	Y		0.6	0.8		0.9	ns
tsk(pr)		İ			1		1	
t <sub>r</sub>	А	Υ					1.5	ns
t <sub>f</sub>	А	Υ					1.5	ns

## t<sub>pd</sub> performance information relative to V<sub>CC</sub> and temperature variation (see Note 4)

Dt <sub>PLH(TA)</sub> †	Temperature drift of tpLH from 0°C to 70°C	-41 ps/10°C
Dt <sub>PHL(TA)</sub> †	Temperature drift of tpHL from 0°C to 70°C	−52 ps/10°C
Dt <sub>PLH(VCC)</sub> ‡	V <sub>CC</sub> drift of t <sub>PLH</sub> from 4.75 V to 5.25 V	28 ps/100 mV
Dt <sub>PHL(VCC)</sub> ‡§	V <sub>CC</sub> drift of t <sub>PHL</sub> from 4.75 V to 5.25 V	20 ps/100 mV

<sup>†</sup> Virtually independent of V<sub>CC</sub>

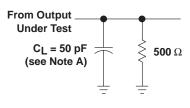
NOTE 4: The data extracted is from a wide range of characterization material.



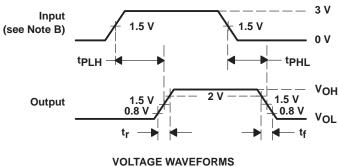
<sup>‡</sup>Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>&</sup>lt;sup>‡</sup> Virtually independent of temperature

#### PARAMETER MEASUREMENT INFORMATION



**LOAD CIRCUIT** 

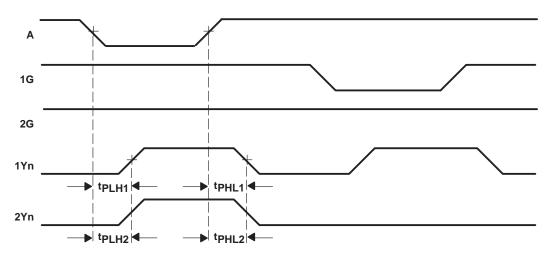


PROPAGATION DELAY TIMES

NOTES: A.  $C_L$  includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms



NOTES: A. Output skew,  $t_{Sk(0)}$ , is calculated as the greater of:

- The difference between the fastest and slowest of tp<sub>LHn</sub> (n = 1, 2)
  The difference between the fastest and slowest of tp<sub>HLn</sub> (n = 1, 2)
- B. Pulse skew,  $t_{Sk(p)}$ , is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  (n = 1, 2).
- C. Process skew,  $t_{sk(pr)}$ , is calculated as the greater of:
  - The difference bétween the fastest and slowest of tpLHn (n = 1, 2) across multiple devices under identical operating conditions
  - The difference between the fastest and slowest of tpHLn (n = 1, 2) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of  $t_{sk(o)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$ 



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CDC341DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples
CDC341DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

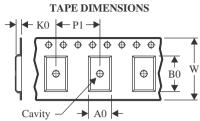
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## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

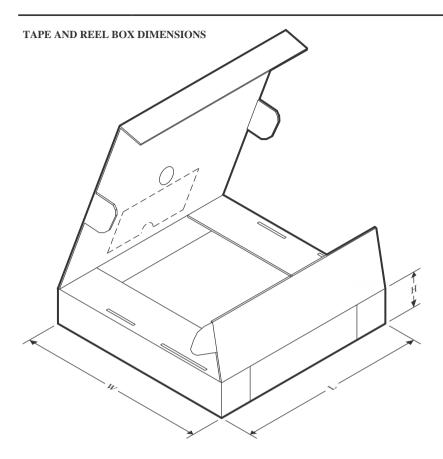


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC341DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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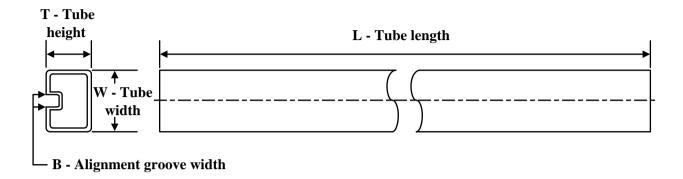
### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CDC341DWR	SOIC	DW	20	2000	367.0	367.0	45.0	

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)	
CDC341DW	DW	SOIC	20	25	507	12.83	5080	6.6	

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